## FEATURES

- Glass passivated chip junction
- Low forward voltage drop
- High surge overload rating of 50 Amperes peak
- Ideal for printed circuit board
- High temperature soldering guaranteed:
$260^{\circ} \mathrm{C}$ for 10 seconds


## MECHANICAL DATA

Case: Molded plastic, DB-S
Epoxy: UL 94V-O rate flame retardant
Terminals: Leads solderable per MIL-STD-202,
method 208 guaranteed
Mounting position: Any
Weight: 0.02 ounce, 0.4 gram


Dimensions in inches and (millimeters)

## Maximum Ratings and Electrical Characteristics

Ratings at $25^{\circ} \mathrm{C}$ ambient temperature unless otherwise specified.
Single phase, half wave, $60 \mathrm{H}_{\mathrm{Z}}$, resistive or inductive load.
For capacitive load, derate current by $20 \%$.

|  | Symbols | DF005S | DF01S | DF02S | DF04S | DF06S | DF08S | DF10S | Units |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: |
| Maximum Recurrent Peak Reverse Voltage | $\mathrm{V}_{\text {RRM }}$ | 50 | 100 | 200 | 400 | 600 | 800 | 1000 | Volts |
| Maximum RMS Voltage | $\mathrm{V}_{\text {RMS }}$ | 35 | 70 | 140 | 280 | 420 | 560 | 700 | Volts |
| Maximum DC Blocking Voltage | $V_{\text {DC }}$ | 50 | 100 | 200 | 400 | 600 | 800 | 1000 | Volts |
| Maximum Average Forward <br> Rectified Current at $\mathrm{T}_{\mathrm{A}}=40^{\circ} \mathrm{C}$ <br> (Note 2) | $\mathrm{I}_{\text {(AV) }}$ | 1.5 |  |  |  |  |  |  | Amp |
| Peak Forward Surge Current, <br> 8.3ms single half-sine-wave <br> superimposed on rated load (JEDEC method) | $\mathrm{I}_{\text {fSM }}$ | 50 |  |  |  |  |  |  | Amp |
| Maximum Forward Voltage at 1.0 A DC and $25^{\circ} \mathrm{C}$ | $V_{\text {F }}$ | 1.1 |  |  |  |  |  |  | Volts |
| Maximum Reverse Current at $\mathrm{T}_{\mathrm{A}}=25^{\circ} \mathrm{C}$ <br> at Rated DC Blocking Voltage $\mathrm{T}_{\mathrm{A}}=125^{\circ} \mathrm{C}$ | $\mathrm{I}_{\mathrm{R}}$ | $\begin{gathered} 5.0 \\ 500 \end{gathered}$ |  |  |  |  |  |  | uAmp |
| Typical Junction Capacitance (Note 1) | $\mathrm{C}_{\text {J }}$ | 25 |  |  |  |  |  |  | pF |
| Typical Thermal Resistance (Note 2) | $\mathrm{R}_{\text {dJA }}$ | 40 |  |  |  |  |  |  | ${ }^{\circ} \mathrm{C} / \mathrm{W}$ |
| Typical Thermal Resistance (Note 2) | $\mathrm{R}_{\text {өJL }}$ | 15 |  |  |  |  |  |  | ${ }^{\circ} \mathrm{C} / \mathrm{W}$ |
| Operating and Storage Temperature Range | $\mathrm{T}_{\mathrm{J}}$, Tstg | -55 to +150 |  |  |  |  |  |  | ${ }^{\circ} \mathrm{C}$ |

## NOTES:

1- Measured at $1 \mathrm{MH}_{\mathrm{Z}}$ and applied reverse voltage of 4.0 VDC .
2- Units mounted on P.C.B. with $0.5 \times 0.5^{\prime \prime}(13 \times 13 \mathrm{~mm})$ copper pads

Fig. 1 - Derating Curve Output Rectified Current


Fig. 3 - Typical Forward Characteristics
Per Leg


Fig. 5-Typical Junction Capacitance Per Leg


Fig. 2 - Maximum Non-Repetitive Peak Forward Surge Current Per Leg


Fig. 4-Typical Reverse Leakage Characteristics Per Leg


Fig. 6 - Typical Transient Thermal Impedance


